



Material Content Data Sheet



Sales Product Name		BSZ110N08NS5		Issued		30. July 2019		
MA#		MA001192606						
Package		PG-TSDSON-8-26		Weight*		36.51 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.419	1.15	1.15	11488	11488
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		67	
	non noble metal	zinc	7440-66-6	0.010	0.03		269	
	non noble metal	iron	7439-89-6	0.197	0.54		5389	
wire	non noble metal	copper	7440-50-8	7.988	21.88	22.46	218822	224547
	noble metal	gold	7440-57-5	0.030	0.08	0.08	815	815
	encapsulation	organic material	carbon black	1333-86-4	0.037	0.10		1022
encapsulation	plastics	epoxy resin	-	1.921	5.26		52627	
	inorganic material	silicondioxide	60676-86-0	16.694	45.74	51.10	457288	510937
	leadfinish	non noble metal	tin	7440-31-5	0.395	1.08	1.08	10827
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	557	557
solder	non noble metal	tin	7440-31-5	0.013	0.04		359	
	noble metal	silver	7440-22-4	0.016	0.04		449	
	non noble metal	lead	7439-92-1	0.626	1.72	1.80	17161	17969
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001	0.00		35	
	non noble metal	zinc	7440-66-6	0.005	0.01		139	
	non noble metal	iron	7439-89-6	0.101	0.28		2774	
heatspreader	non noble metal	copper	7440-50-8	4.112	11.26	11.55	112649	115597
	inorganic material	phosphorus	7723-14-0	0.001	0.00		32	
	non noble metal	zinc	7440-66-6	0.005	0.01		129	
heatspreader	non noble metal	iron	7439-89-6	0.094	0.26		2574	
	non noble metal	copper	7440-50-8	3.816	10.45	10.72	104528	107263
	*deviation	< 10%				Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com